

## ABSTRACT OF THE DISCLOSURE

The high thermal conductive aluminum nitride sintered body according to the present invention has: a thermal conductivity of  $220 \text{ W/m} \cdot \text{K}$  or more; and a three point bending strength of  $250 \text{ MPa}$  or more; wherein a ratio ( $I_{\text{Al}_2\text{Y}_4\text{O}_9}/I_{\text{AlN}}$ ) of X-ray diffraction intensity ( $I_{\text{Al}_2\text{Y}_4\text{O}_9}$ ) of  $\text{Al}_2\text{Y}_4\text{O}_9$  (201 plane) with respect to X-ray diffraction intensity ( $I_{\text{AlN}}$ ) of aluminum nitride (101 plane) is 0.002 to 0.03. According to the foregoing structure, there can be provided an aluminum nitride sintered body having a high thermal conductivity and excellent heat radiating property.